



Final Product Change Notification

201908007F01U01

Issue Date: 12-Feb-2020
Effective Date: 12-May-2020

UPDATE

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.



QUALITY

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

**UPDATE: NXP-ATKL TEPBGA 27*27
Package Substrate Singulation
Method Change From Mechanical
Punch To Saw**

Description of Change

NXP Semiconductors announces the change of substrate singulation method from mechanical punch to saw for the TEPBGA 27*27 package assembled in NXP-ATKL, Kuala Lumpur, Malaysia assembly facility.
For more information about the substrate singulation method change, please refer to the "Communication Package" file attached.

The above change coincides with DeQuMa ID: SEM-PA-14 and SEM-EQ-01.

Reason for Change

The substrate singulation method change is required for customer supply assurance.

Identification of Affected Products

Product part number and marking identification does not change.

A visual comparison between substrate singulation using mechanical punch and saw is provided in the "Communication Package" file attached.

Product Availability

Sample Information

Samples are available upon request

Sample part numbers information is available in the "Communication Package" file attached.

Production

Planned first shipment 20-Dec-2019

Update Information

NXP Semiconductors is issuing an update to PCN_201908007F01 previously distributed on 05-September-2019 to remove SnPb part numbers from the affected product list of the notification.

These SnPb parts will have no change to the process as described in the original PCN and will utilize the current substrate and mechanical punch for singulation in production.

The SnPb part numbers that are not affected by PCN_201908007F01 are attached with this notification.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 13-Mar-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Affected OPN**Affected 12NC**

SPC5566MZP144	935309958557
SPC5566MZP132	935313983557
SPC5674FF3MVV3	935310677557
SPC5674FF3MVV3R	935310677518